2.5 V/3.3 V/5.0 V Differential **Data/Clock D Flip-Flop** with Reset

Multi-Level Inputs to LVPECL Translator w/ Internal Termination

The NB4L52 is a differential Data and Clock D flip-flop with a differential asynchronous Reset. The differential inputs incorporate internal 50 Ω termination resistors and will accept PECL, LVPECL, LVCMOS, LVTTL, CML, or LVDS logic levels. When Clock transitions from Low to High, Data will be transferred to the differential LVPECL outputs. The differential Clock inputs allow the NB4L52 to also be used as a negative edge triggered device. The device is housed in a small 3x3 mm 16 pin QFN package.

Features

- Maximum Input Clock Frequency > 4 GHz Typical
- 330 ps Typical Propagation Delay
- 145 ps Typical Rise and Fall Times
- Differential LVPECL Outputs, 750 mV Peak-to-Peak, Typical
- Operating Range: $V_{CC} = 2.375 \text{ V}$ to 5.5 V with $V_{EE} = 0 \text{ V}$
- Internal Input Termination Resistors, 50 Ω
- Functionally Compatible with Existing 2.5 V/3.3 V/5.0 V LVEL, LVEP, EP, and SG Devices
- -40°C to +85°C Ambient Operating Temperature
- These are Pb-Free Devices



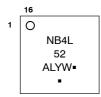
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MARKING DIAGRAM*



QFN-16 MN SUFFIX CASE 485G



= Assembly Location

= Wafer Lot = Year = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

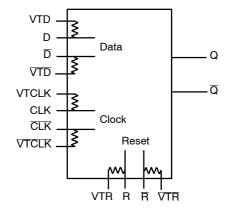


Figure 1. Logic Diagram

Table 1. TRUTH TABLE

R	D	CLK	Q
Н	х	х	L
L	L	Z	L
L	Н	Z	Н

Z = LOW to HIGH Transition

x = Don't Care

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

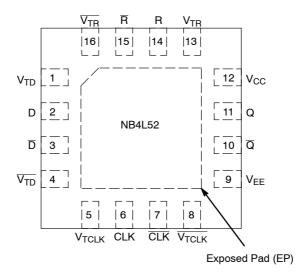


Figure 2. Pinout (Top View)

Table 2. PIN DESCRIPTION

	able 2. FIN DESCRIPTION						
Pin	Name	I/O	Description				
1	V_{TD}	-	Internal 50 Ω Termination Pin. (See Table 4)				
2	D	ECL, CML, LVCMOS, LVDS, LVTTL Input	Noninverted Differential Input. (Note 1)				
3	D	ECL, CML, LVCMOS, LVDS, LVTTL Input	Inverted Differential Input. (Note 1)				
4	$\overline{V_{TD}}$	-	Internal 50 Ω Termination Pin. (See Table 4)				
5	V _{TCLK}	-	Internal 50 Ω Termination Pin. (See Table 4)				
6	CLK	ECL, CML, LVCMOS, LVDS, LVTTL Input	Noninverted Differential Input. (Note 1)				
7	CLK	ECL, CML, LVCMOS, LVDS, LVTTL Input	Inverted Differential Input. (Note 1)				
8	V _{TCLK}	-	Internal 50 Ω Termination Pin. (See Table 4)				
9	V _{EE}	-	Negative Supply Voltage				
10	Q	ECL Output	Inverted Differential Output. Typically terminated with 50 Ω resistor to V $_{CC}$ – 2.0 V.				
11	Q	ECL Output	Noninverted Differential Output. Typically terminated with 50 Ω resistor to V $_{CC}$ – 2.0 V.				
12	V _{CC}	-	Positive Supply Voltage				
13	V_{TR}	-	Internal 50 Ω Termination Pin. (See Table 4)				
14	R	LVECL, LVCMOS, LVTTL Input	Noninverted Differential Reset Input. (Note 1)				
15	R	LVECL, LVCMOS, LVTTL Input	Inverted Differential Reset Input. (Note 1)				
16	$\overline{V_{TR}}$	-	Internal 50 Ω Termination Pin. (See Table 4)				
_	EP	-	The Exposed Pad (EP) on the QFN–16 package bottom is thermally connected to the die for improved heat transfer out of package. The pad is not electrically connected to the die, but is recommended to be electrically and thermally connected to V_{EE} on the PC board.				

^{1.} In the differential configuration when the input termination pin (VTD, VTD, VTR, VTR, VTCLK, VTCLK) are connected to a common termination voltage or left open, and if no signal is applied on D/D,CLK/CLK,R/R input then the device will be susceptible to self–oscillation.

Table 3. ATTRIBUTES

Charac	Va	lue		
ESD Protection	Human Body Model Machine Model Charged Device Model	> 2 kV > 200 V > 1 kV		
Moisture Sensitivity (Note 2)		Pb Pkg	Pb-Free Pkg	
	QFN-16	Level 1	Level 1	
Flammability Rating Oxygen Inde	ex: 28 to 34	UL 94 V-0	@ 0.125 in	
Transistor Count			64	
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test				

^{2.} For additional information, see Application Note AND8003/D.

Table 4. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	Positive Power Supply	V _{EE} = 0 V		6.0	V
V _{EE}	Negative Power Supply	V _{CC} = 0 V		-6.0	V
V _{IO}	Positive Input/Output Negative Input/Output	V _{EE} = 0 V V _{CC} = 0 V	$V_{I} \leq V_{CC}$ $V_{I} \geq V_{EE}$	6.0 -6.0	V
I _{IN}	Input Current Through R_T (50 Ω Resistor)	Static Surge		45 80	mA mA
l _{out}	Output Current	Continuous Surge		25 50	mA mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 LFPM 500 LFPM	16 QFN 16 QFN	42 35	°C/W °C/W
$\theta_{\sf JC}$	Thermal Resistance (Junction-to-Case)	2S2P (Note 3)	16 QFN	4.0	°C/W
T _{sol}	Wave Solder Pb-Free			265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

3. JEDEC standard multilayer board – 2S2P (2 signal, 2 power) with 8 filled thermal vias under exposed pad.

Table 5. DC CHARACTERISTICS, CLOCK INPUTS, LVPECL OUTPUTS

 $(V_{CC} = 2.375 \text{ V to } 5.5 \text{ V}, V_{EE} = 0 \text{ V or } V_{CC} = 0 \text{ V}, V_{EE} = -2.375 \text{ to } -5.5 \text{ V}, T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C})$

Symbol	Characteristic	Min	Тур	Max	Unit
I _{EE}	Power Supply Current (Inputs and Outputs Open)		16	25	mA
V _{OH}	Output HIGH Voltage (Note 4, 5) $V_{CC} = 5.0 \text{ V}$ $V_{CC} = 3.3 \text{ V}$ $V_{CC} = 2.5 \text{ V}$	V _{CC} - 1145 3855 2155 1355	V _{CC} - 1020 3980 2280 1480	V _{CC} - 895 4105 2405 1605	mV
V _{OL}	Output LOW Voltage (Note 4, 5) $V_{CC} = 5.0V$ $V_{CC} = 3.3V$ $V_{CC} = 2.5V$	V _{CC} - 1945 3055 1355 555	V _{CC} - 1770 3230 1530 730	V _{CC} - 1600 3400 1700 900	mV

DIFFERENTIAL INPUT DRIVEN SINGLE-ENDED (Figures 4 & 7)

Vth	Input Threshold Reference Voltage Range (Note 6)	1050	V _{CC} – 150	mV
V _{IH}	Single-ended Input HIGH Voltage	Vth + 150	V _{CC}	mV
V _{IL}	Single-ended Input LOW Voltage	V _{EE}	Vth - 150	mV

DIFFERENTIAL INPUT DRIVEN DIFFERENTIALLY (Figures 5, 6 & 8)

V _{IHD}	Differential Input HIGH Voltage	1200		V _{CC}	mV
V _{ILD}	Differential Input LOW Voltage	V _{EE}		V _{CC} – 150	mV
V _{CMR}	Input Common Mode Range (Differential Configuration) (Note 7)	1125		V _{CC} – 75	mV
V _{ID}	Differential Input Voltage (V _{IHD} V _{ILD})	150		V _{CC}	mV
I _{IH}	Input HIGH Current D / D, CLK / CLK, R /R (VTx/VTx Open	-150		150	μΑ
I _{IL}	Input LOW Current D / D, CLK / CLK, R /R (VTx/VTx Open	-150		150	μΑ
R _{TIN}	Internal Input Termination Resistor	40	50	60	Ω

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 4. LVPECL outputs loaded with 50 Ω to V_{CC} 2.0 V for proper operation.
- 5. Input and output parameters vary 1:1 with V_{CC}.
 6. V_{th} is applied to the complementary input when operating in single-ended mode.
- 7. V_{CMRMIN} varies 1:1 with V_{EE}, V_{CMRMAX} varies 1:1 with V_{CC}. The V_{CMR} range is referenced to the most positive side of the differential input signal.

Table 6. AC CHARACTERISTICS V_{CC} = 2.375 V to 5.5 V; V_{EE} = 0 V or V_{CC} = 0 V, V_{EE} = -2.375 to -5.5 V (Note 8)

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
V _{OUTPP}	$ \begin{array}{ll} \text{Output Voltage Amplitude (@V_{INPPmin})} \\ \text{(Note 10) (See Figure 4)} & f_{in} \leq 2.0 \text{ GHz} \\ & f_{in} \leq 3.0 \text{ GHz} \\ & f_{in} \leq 4.0 \text{ GHz} \end{array} $	530 490 380	770 720 580		530 490 380	780 730 580		530 490 380	760 680 530		mV
t _{PLH} , t _{PHL}	Propagation Delay to CLK to Q, R to Q Output Differential	300	400	500	300	400	500	300	400	500	ps
t _s	Setup Time	100			100			100			ps
t _h	Hold Time	50			50			50			ps
t _{RR}	Reset Recovery	400			400			400			ps
t _{PW}	Minimum Pulse Width R/R	250			250			250			ps
[†] JITTER	RMS Random Clock Jitter (Note 9) $ \begin{aligned} f_{in} &\leq 2.0 \text{ GHz} \\ f_{in} &\leq 3.0 \text{ GHz} \\ f_{in} &\leq 4.0 \text{ GHz} \end{aligned} $		1 1 1			1 1 1			1 1 1		ps
V _{INPP}	Input Voltage Swing/Sensitivity (Differential Configuration) (Note 10)	150		2800	150		2800	150		2800	mV
t _r t _f	Output Rise/Fall Times @ 0.5 GHz (20% – 80%)	80	135	190	80	145	190	80	155	190	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

Additive RMS jitter with 50% duty cycle clock signal.
 Input and output voltage swing is a single-ended measurement operating in differential mode.

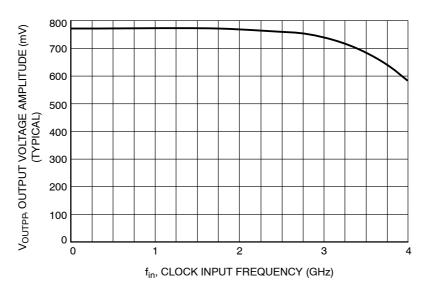
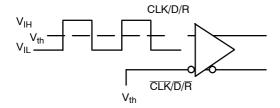


Figure 3. Output Voltage Amplitude (V_{OUTPP}) vs. Clock Input Frequency at Ambient Temperature (Typical).

^{8.} Measured by forcing V_{INPP} (MIN) from a 50% duty cycle clock source. All loading with an external R_L = 50 Ω to V_{CC} – 2.0 V. Input edge rates 40 ps (20% - 80%).



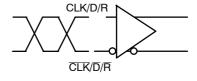


Figure 4. Differential Input Driven Single-Ended

Figure 5. Differential Inputs Driven Differentially

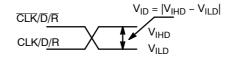
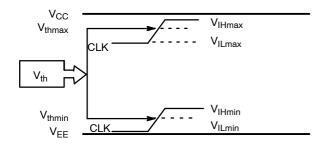


Figure 6. Differential Inputs Driven Differentially





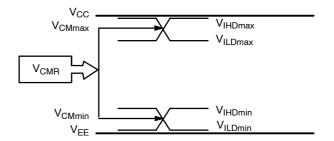


Figure 8. V_{CMR} Diagram

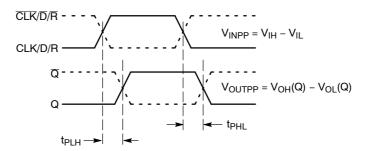


Figure 9. AC Reference Measurement

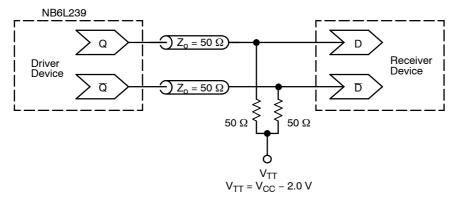


Figure 10. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

ORDERING INFORMATION

Device	Package	Shipping [†]
NB4L52MNG	QFN-16, 3 x 3 mm (Pb-Free)	123 Units / Rail
NB4L52MNR2G	QFN-16, 3 x 3 mm (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D - ECL Clock Distribution Techniques

AN1406/D - Designing with PECL (ECL at +5.0 V)

AN1503/D - ECLinPS I/O SPiCE Modeling Kit

AN1504/D - Metastability and the ECLinPS Family
AN1568/D - Interfacing Between LVDS and ECL

AN1672/D - The ECL Translator Guide

AND8001/D - Odd Number Counters Design

AND8002/D - Marking and Date Codes

AND8020/D - Termination of ECL Logic Devices

AND8066/D - Interfacing with ECLinPS

AND8090/D - AC Characteristics of ECL Devices

The products described herein (NB4L52), may be covered by U.S. patents including 6,362,644. There may be other patents pending.

回

TOP VIEW

┅┅

SIDE VIEW

DETAIL B

LEA

A1

PIN ONE

LOCATION

2X 0.10 C

2X 0.10 C

// 0.05 C

□ 0.05 C

NOTE 4





Α

В

SEATING PLANE

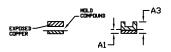
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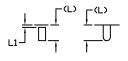
DATE 08 OCT 2021

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DIMENSION 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS.
 THE TERMINALS.



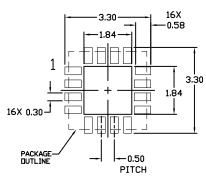
DETAIL B
ALTERNATE
CONSTRUCTIONS

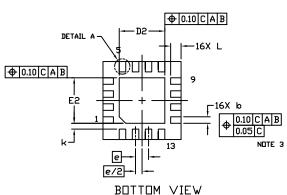


DETAIL A
ALTERNATE TERMINAL
CONSTRUCTIONS

	MILLIME	TERS			
DIM	MIN.	N□M.	MAX.		
Α	0.80	0.90	1.00		
A1	0.00	0.03	0.05		
АЗ		0.20 REF			
b	0.18 0.24 0.30				
D	3.00 BSC				
DS	1.65	1.85			
E		3.00 BSC	;		
E2	1.65 1.75 1.85				
е	0.50 BSC				
k	0.18 TYP				
L	0.30	0.40	0.50		
L1	0.00	0.08	0.15		

MOUNTING FOOTPRINT





GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code A = Assembly Location

L = Wafer Lot
Y = Year
W = Work Week
■ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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